

Title (en)  
DISTRIBUTION SYSTEM FOR A PROCESS FLUID FOR CHEMICAL AND/OR ELECTROLYTIC SURFACE TREATMENT OF A SUBSTRATE

Title (de)  
VERTEILUNGSSYSTEM FÜR EINE PROZESSFLÜSSIGKEIT ZUR CHEMISCHEN UND/ODER ELEKTROLYTISCHEN  
OBERFLÄCHENBEHANDLUNG EINES SUBSTRATS

Title (fr)  
SYSTÈME DE DISTRIBUTION D'UN FLUIDE DE TRAITEMENT POUR TRAITEMENT DE SURFACE CHIMIQUE ET/OU ÉLECTROLYTIQUE  
D'UN SUBSTRAT

Publication  
**EP 3872236 A1 20210901 (EN)**

Application  
**EP 20160190 A 20200228**

Priority  
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Abstract (en)  
The invention relates to a distribution system for a process fluid for chemical and/or electrolytic surface treatment of a substrate, a distribution method for a process fluid for chemical and/or electrolytic surface treatment of a substrate and a data processing device. The distribution system for a process fluid for chemical and/or electrolytic surface treatment of a substrate comprises a distribution body and a shield element. The distribution body comprises a plurality of openings for the process fluid. The shield element is configured to at least partially cover at least one of the plurality of openings to limit a flow of the process fluid through the distribution body.

IPC 8 full level  
**C25D 5/08** (2006.01); **C25D 17/00** (2006.01); **C25D 21/12** (2006.01)

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**C23C 18/1628** (2013.01 - KR); **C25D 5/08** (2013.01 - EP KR US); **C25D 17/008** (2013.01 - EP KR US); **C25D 21/12** (2013.01 - EP KR US)

Citation (applicant)  
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Citation (search report)  
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Designated contracting state (EPC)  
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DOCDB simple family (publication)  
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**EP 20160190 A 20200228**; CN 202180016728 A 20210226; EP 2021054934 W 20210226; EP 21707297 A 20210226; JP 2022551800 A 20210226; KR 20227027963 A 20210226; PL 20160190 T 20200228; PT 20160190 T 20200228; TW 110115822 A 20210430; US 202117800287 A 20210226